

OSRAM LZP-04UB0R

Datasheet

Discontinued

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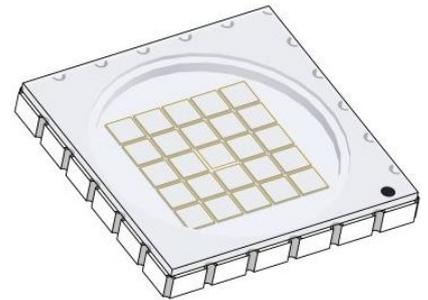
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LED ENGIN LuxiGen®

LZP-04UB0R



The LZP Violet LED emitter provides superior radiometric power in 5nm wavelength bins. With a small 12.0 mm x 12.0 mm footprint, this package provides exceptional radiant flux density. The patented design has unparalleled thermal and optical performance. The high quality materials used in the package are chosen to optimize flux output, have excellent resistance to UV, and minimize stresses - which results in a superior reliability and radiant flux maintenance.



Applications

- Appliances & Tools
- Material Processing
- Medical Lighting

Features

- Package: Ceramic package with integrated glass window
- Chip technology: UX:3
- Typ. Radiation: 120°
- Color: $\lambda_{\text{peak}} = 395 \text{ nm}$ (• violet); $\lambda_{\text{peak}} = 395 \text{ nm}$ (• violet); $\lambda_{\text{peak}} = 395 \text{ nm}$ (• violet); $\lambda_{\text{peak}} = 395 \text{ nm}$ (• violet)

Ordering Information

Type	Brightness ¹⁾	Ordering Code
LZP-04UB0R-00U4		Q65113A2059
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
LZP-04UB0R-00U5		Q65113A2060
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
LZP-04UB0R-00U8		Q65113A2061
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	
• violet	• $\Phi_E = 3.8 \dots 7.5 \text{ W}$ ($I_F = 700 \text{ mA}$)	

Maximum Ratings

Parameter	Symbol		Values			
			• violet	• violet	• violet	• violet
Operating Temperature	T_{op}	min.	-40 °C	-40 °C	-40 °C	-40 °C
		max.	100 °C	100 °C	100 °C	100 °C
Storage Temperature	T_{stg}	min.	-40 °C	-40 °C	-40 °C	-40 °C
		max.	100 °C	100 °C	100 °C	100 °C
Junction Temperature ²⁾	T_j	max.	130 °C	130 °C	130 °C	130 °C
Forward Current ²⁾	I_F	max.	1000 mA	1000 mA	1000 mA	1000 mA
Forward Current pulsed $t \leq 10 \text{ ms}$; $D \leq 0.1$; $T_C = 25 \text{ °C}$	$I_{F \text{ pulse}}$	max.	1000 mA	1000 mA	1000 mA	1000 mA
ESD withstand voltage acc. ANSI/ESDA/JEDEC JS-001 (HBM, Class 0)	V_{ESD}		ESD sensitive device	ESD sensitive device	ESD sensitive device	ESD sensitive device
Reverse voltage ³⁾	V_R		Not designed for reverse operation			

Characteristics

$I_F = 700 \text{ mA}$; $T_C = 25 \text{ °C}$; per string

Parameter	Symbol		Values	Values	Values	Values
			• violet	• violet	• violet	• violet
Total radiant flux ⁴⁾	Φ_E	typ.	22.5 W	22.5 W	22.5 W	22.5 W
Peak Wavelength ⁵⁾ $I_F = 700 \text{ mA}$	λ_{peak}	min.	385 nm	385 nm	385 nm	385 nm
		typ.	395 nm	395 nm	395 nm	395 nm
		max.	410 nm	410 nm	410 nm	410 nm
Viewing angle at 50% I_V	2ϕ	typ.	115 °	115 °	115 °	115 °
Forward Voltage ⁶⁾⁴⁾ $I_F = 700 \text{ mA}$	V_F	min.	19.20 V	19.20 V	19.20 V	19.20 V
		typ.	22.50 V	22.50 V	22.50 V	22.50 V
		max.	25.20 V	25.20 V	25.20 V	25.20 V
Reverse current ³⁾	I_R		Not designed for reverse operation	Not designed for reverse operation	Not designed for reverse operation	Not designed for reverse operation
Electrical thermal re- sistance junction/case	$R_{\text{thJC elec.}}$	typ.	0.60 K / W			

Brightness Groups

per string

- violet

Group	Total radiant flux ¹⁾	Total radiant flux ¹⁾
	$I_F = 700 \text{ mA}$ min. Φ_E	$I_F = 700 \text{ mA}$ max. Φ_E
T	3.8 W	4.8 W
U	4.8 W	6.0 W
V	6.0 W	7.5 W

Wavelength Groups

per string

- violet

Group	Peak Wavelength ⁵⁾	Peak Wavelength ⁵⁾
	$I_F = 700 \text{ mA}$ min. λ_{peak}	$I_F = 700 \text{ mA}$ max. λ_{peak}
U4	385 nm	390 nm
U5	390 nm	395 nm
U8	405 nm	410 nm

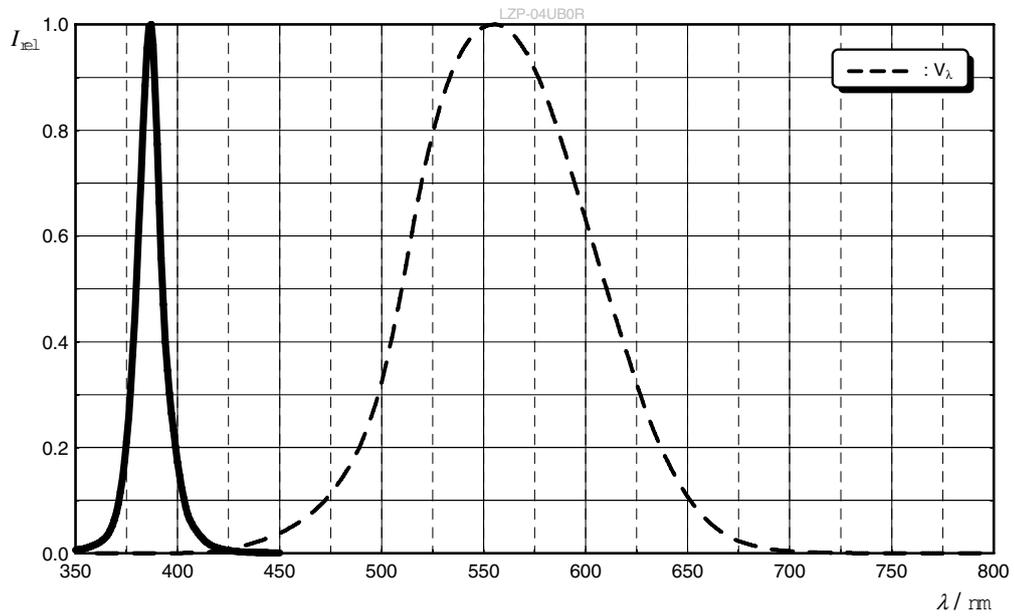
Group Name on Label

Example: T-U4

Brightness	Wavelength
T	U4

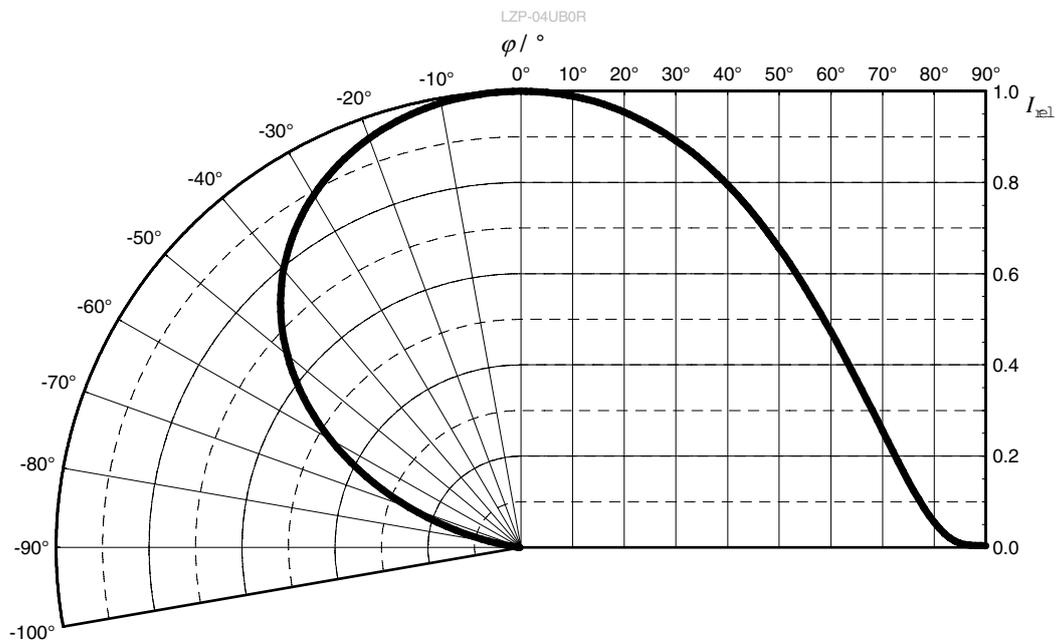
Relative Spectral Emission ⁴⁾

$I_{rel} = f(\lambda)$; $I_F = 700 \text{ mA}$; $T_C = 25 \text{ }^\circ\text{C}$



Radiation Characteristics ⁴⁾

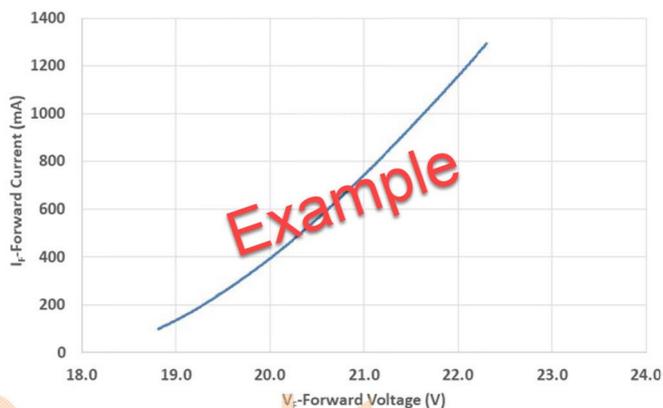
$I_{rel} = f(\phi)$; $T_C = 25 \text{ }^\circ\text{C}$



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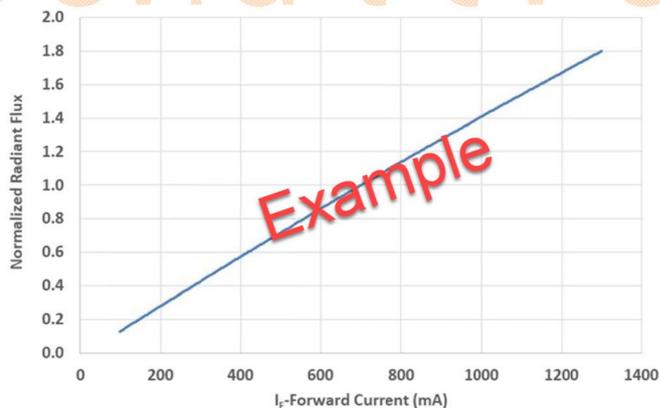
Forward current ⁴⁾

$$I_F = f(V_F); T_C = 25\text{ °C}$$



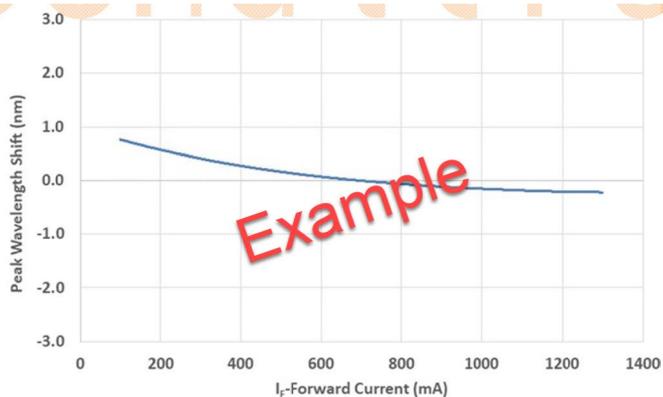
Relative Luminous Flux ^{4), 7)}

$$\Phi_E / \Phi_E(700\text{ mA}) = f(I_F); T_C = 25\text{ °C}$$



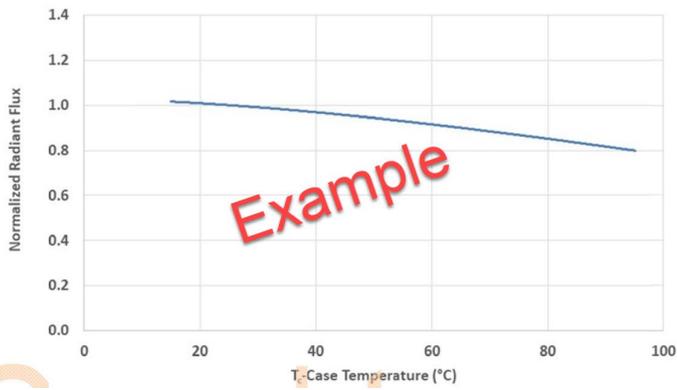
Peak Wavelength ⁴⁾

$$\Delta\lambda_{\text{peak}} = f(I_F); T_C = 25\text{ °C}$$



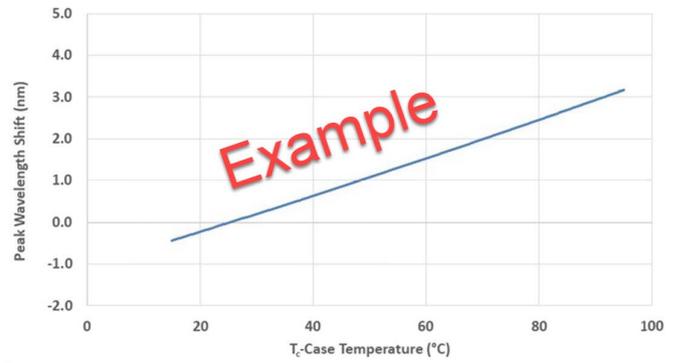
Relative Luminous Flux ⁴⁾

$$\Phi_E / \Phi_E(25\text{ °C}) = f(T_j); I_F = 700\text{ mA}$$



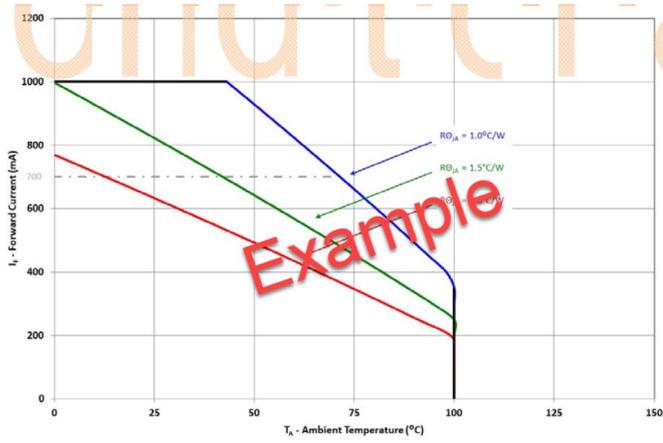
Peak Wavelength ⁴⁾

$$\Delta\lambda_{\text{peak}} = \lambda_{\text{peak}} - \lambda_{\text{peak}}(25\text{ °C}) = f(T_j); I_F = 700\text{ mA}$$

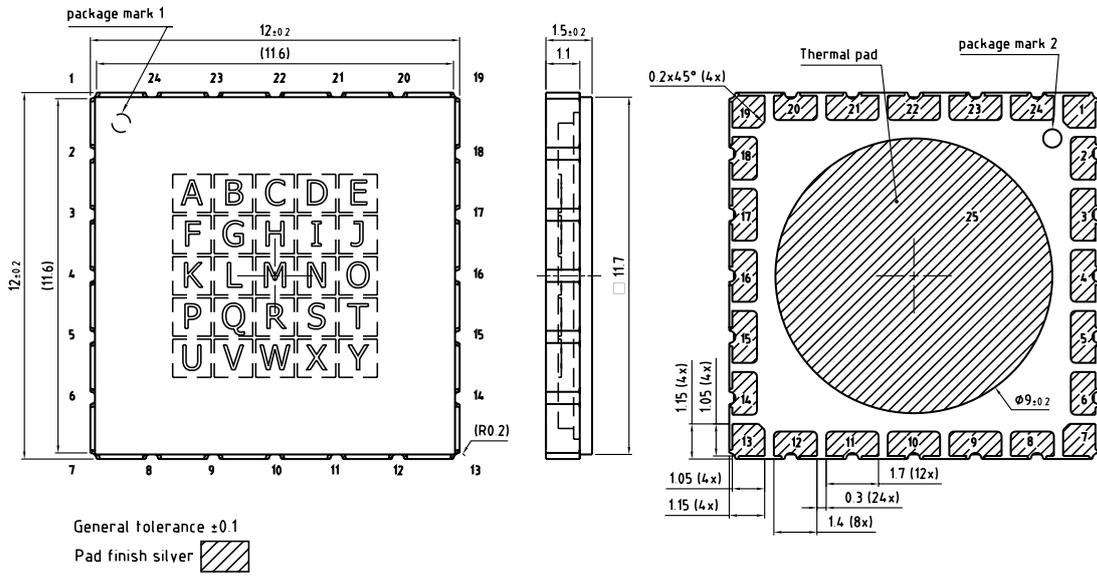


Max. Permissible Forward Current ⁸⁾

$I_F = f(T)$; • violet



Dimensional Drawing ⁹⁾



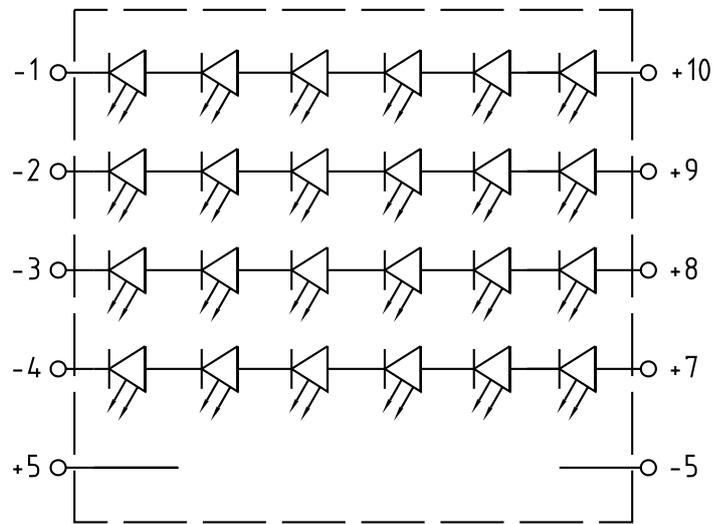
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Further Information:

Approximate Weight: 513.3 mg

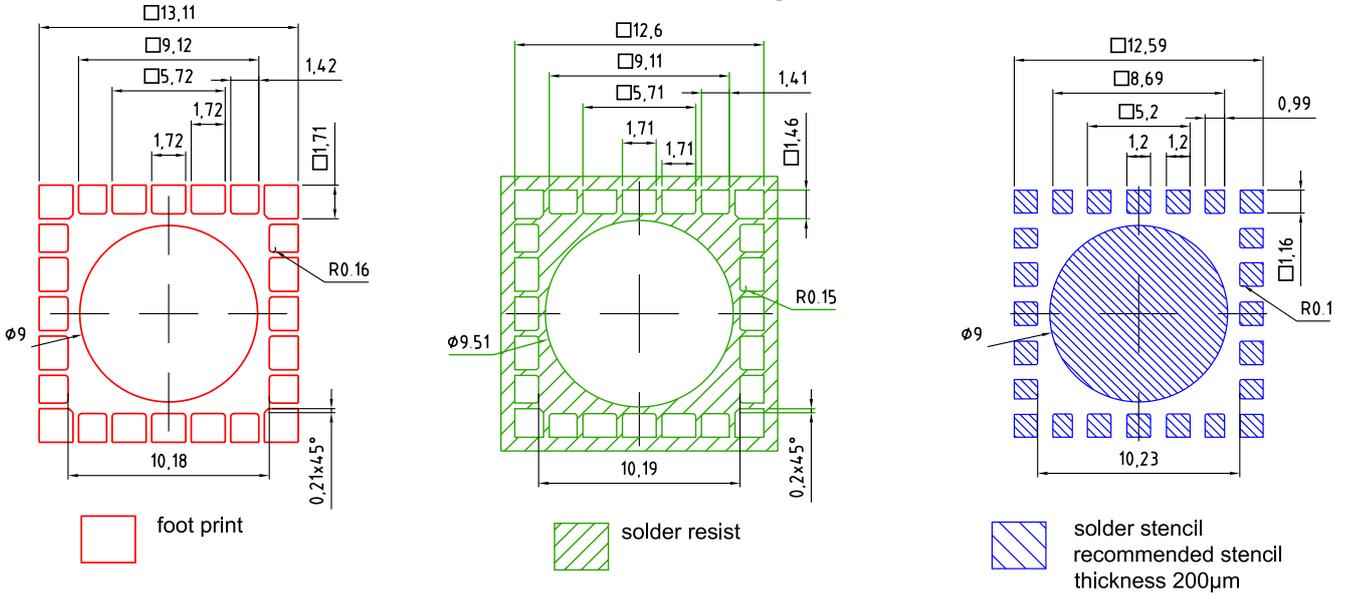
Electrical Internal Circuit

Pin Out		
Pad	Channel	Function
24	1	Anode
18		Cathode
3	2	Anode
17		Cathode
5	3	Anode
15		Cathode
8	4	Anode
14		Cathode

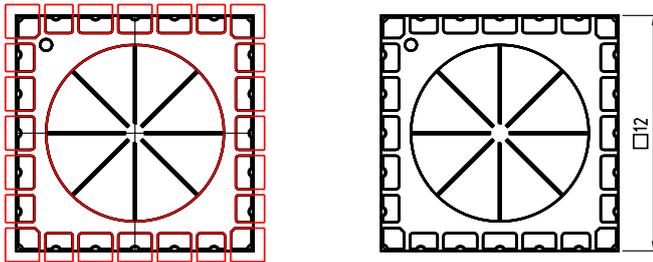


Recommended Solder Pad ⁹⁾

Pedestal MCPCB Design



Component Location on Pad

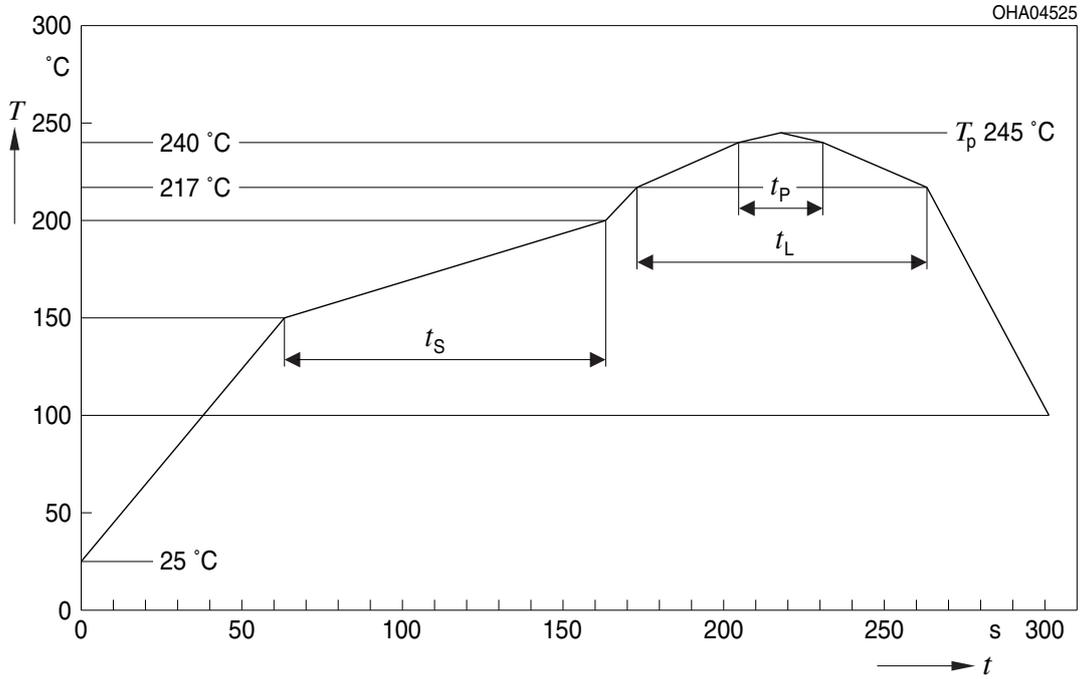


E062.3010.303-01

1. For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere.
2. Package not suitable for ultra sonic cleaning.
3. Pedestal MCPCB allows the emitter thermal slug to be soldered directly to the metal core of the MCPCB. Such MCPCB eliminate the high thermal resistance dielectric layer that standard MCPCB technologies use in between the emitter thermal slug and the metal core of the MCPCB, thus lowering the overall system thermal resistance.
4. X-ray sample monitoring for solder voids underneath the emitter thermal slug is recommended. The total area covered by solder voids should be less than 20% of the total emitter thermal slug area. Excessive solder voids will increase the emitter to MCPCB thermal resistance and may lead to higher failure rates due to thermal over stress.

Reflow Soldering Profile

Product complies to MSL Level 1 acc. to JEDEC J-STD-020E

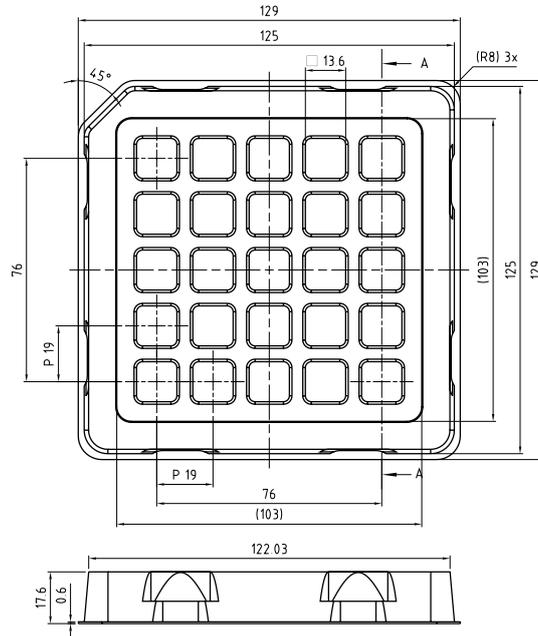


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	250	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	4	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component
^{*)} slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

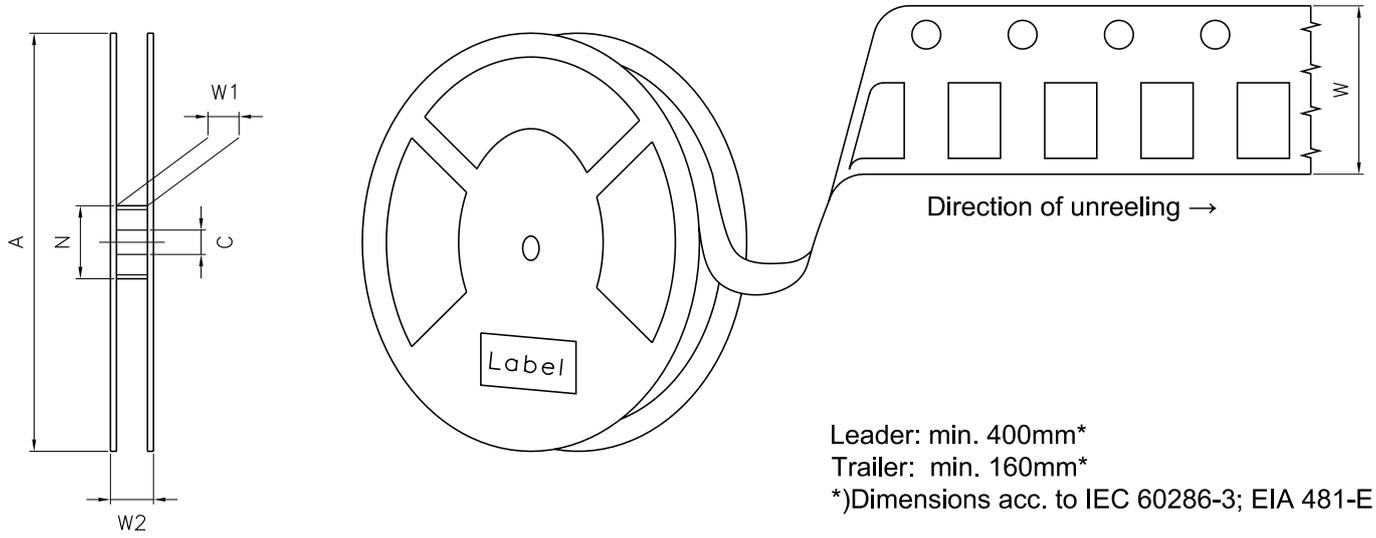
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Taping ⁹⁾



C67062-A0384-X2-01

Tape and Reel ¹⁰⁾



Reel Dimensions

A	W	N _{min}	W ₁	W _{2 max}	Pieces per PU
					25

Barcode-Product-Label (BPL)

OSRAM
Opto Semiconductors
Our Brand

LED ENGINE

(6P) Batch No: 1234567890
(1T) Lot No: 1234567890
(X) Prod No: 12345678
(9D) D/C : 1234
(Q) Qty: 9999
CoO: XX

LXX-XXXXX BIN1: XXX-X-X-XXX
XxxXxx BIN2: XXX-X-X-XXX
RoHS Compliant BIN3: XX-X-X-XXX
BIN4: XXX-XXX-X-XXX
BIN5: X-XX-X-XXX
BIN6: X-XX-X-XXX

ML TEMP ST
X XXX° X

Pack: RXX
B_X123_12345.1234
001





Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **high risk (exposure time less than 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

Tapes and reels are shipped in airtight bags in order to reduce the onset of silver tarnish. We recommend bags only be opened when ready to use emitters. Partially used reels or trays should be stored in airtight bags or in storage purged with nitrogen.

Based on very short life cycle times in chip technology this component is subject to frequent adaption to the latest chip technology.

Changes to the content of this datasheet may occur without further notification. JEDEC 46C constitutes the guideline of the change management for the device specified in this document.

For further application related information please visit <https://ams-osram.com/support/application-notes>

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness groups are tested at a current pulse duration of 10 ms and a tolerance of $\pm 10\%$.
- 2) **Operating Conditions:** Operating conditions according DC-derating (Max. Permissible Forward Current)
- 3) **Reverse Operation:** Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
- 4) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 5) **Peak Wavelength:** Wavelengths are tested at a current pulse duration of 10 ms and a tolerance of ± 2 nm.
- 6) **Forward Voltage:** Forward voltages are tested at a current pulse duration of 10 ms and a tolerance of ± 0.1 V.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ) used for Derating.
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.3	2020-10-02	Initial Version
1.4	2023-06-28	Discontinued

Discontinued



EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，
不含有毒有害物质或元素。

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